

# SOT852-2

plastic thermal enhanced very thin quad flat package; no leads; 68 terminals; body 8 x 8 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN68
<b>Package type industry code</b>	HVQFN68
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-5-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	68	-	

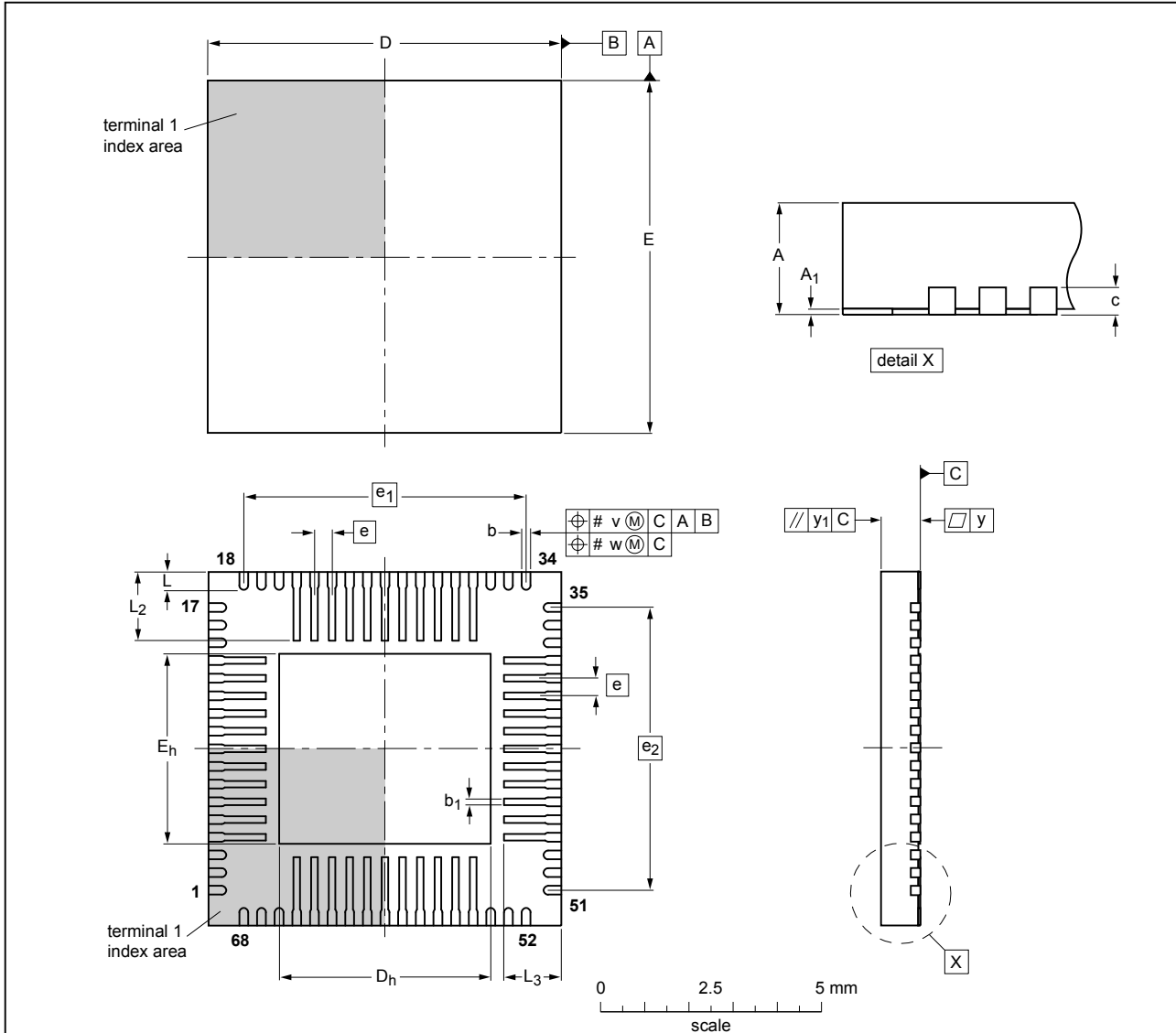


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## 2. Package outline

HVQFN68: plastic thermal enhanced very thin quad flat package; no leads; 68 terminals; body 8 x 8 x 0.85 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max	A <sub>1</sub>	b	b <sub>1</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	L <sub>2</sub>	L <sub>3</sub>	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.25 0.15	0.2 0.1	0.2	8.1 7.9	4.95 4.65	8.1 7.9	4.45 4.15	0.4	6.4	6.4	0.5 0.3	1.65 1.45	1.4 1.2	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT852-2	---	---	---			05-04-21 05-05-23

Fig. 1. Package outline HVQFN68 (SOT852-2)

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### 3. Legal information

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Date of release: 8 February 2016

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